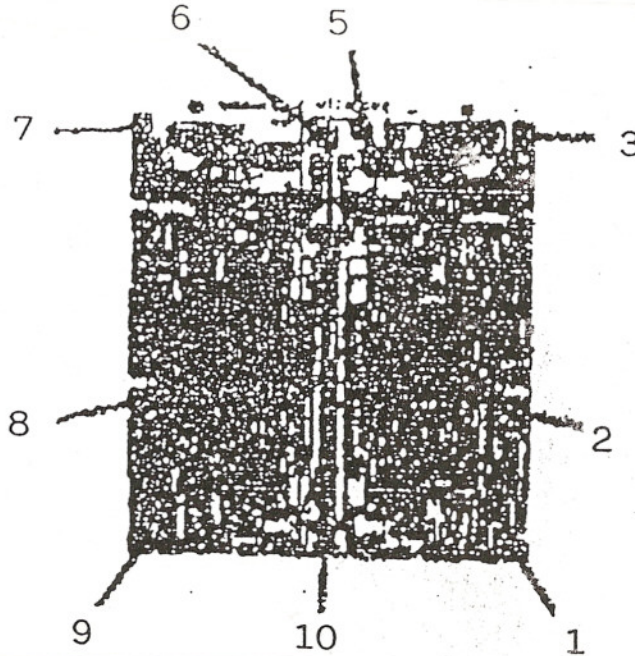




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function	Pad	Function
1	D1	6	V-
2	S1	7	In2
3	In1	8	S2
4	NC	9	D2
5	GND	10	V+

Chip back must be connected to V+.

Topside Metal: Al
Backside: Si
Backside Potential: V +
Mask Ref: 6222A
Bond Pads : .004" x .004"

APPROVED BY: CD
MFG: Harris

DIE SIZE : .098" x .088"
THICKNESS: .020"

DATE: 6/28/02
P/N: DG300A

DG 10.1.2
 Rev A 3-4-99